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## U.S. UTILITY Patent Application

APPL NUM 10075043	FILING DATE 02/12/2002	CLASS 438	SUBCLASS -	GAU 2812	EXAMINER <i>[Signature]</i>
<b>**APPLICANTS:</b> Tseng David; Huang Chien-Ping; Huang Kun-Ming;					
<b>**CONTINUING DATA VERIFIED:</b>					
<b>** FOREIGN APPLICATIONS VERIFIED:</b> TAIWAN TW 90133149 12/31/2001					
PG-PUB <input type="checkbox"/> DO NOT PUBLISH <input type="checkbox"/>		RESCIND <input type="checkbox"/>			
Foreign priority claimed <input type="checkbox"/> yes <input type="checkbox"/> no		35 USC 119 conditions met <input type="checkbox"/> yes <input type="checkbox"/> no		ATTORNEY DOCKET NO	
Verified and Acknowledged Examiners's initials		56956 (71987)			
TITLE : Method and system of wire bonding for use in fabrication of semiconductor package <small>U.S. DEPT. OF COMM./PAT. &amp; TM.-PTO-436L (Rev. 12-94)</small>					

<b>NOTICE OF ALLOWANCE MAILED</b>		<b>CLAIMS ALLOWED</b>	
		Total Claims	Print Claim for O.G
Assistant Examiner		<b>DRAWING</b>	
<b>ISSUE FEE</b>		Sheets Drwg.	Figs. Drwg.
Amount Due	Date Paid	Print Fig.	
		Application Examiner	
<input type="checkbox"/> <b>TERMINAL DISCLAIMER</b>		<b>PREPARED FOR ISSUE</b> WARNING: The information disclosed herein may be restricted. Unauthorized disclosure may be prohibited by the United States Code Title 35, Sections 122, 181 and 368, Possession outside the U.S. Patent & Trademark Office is restricted to authorized employees and contractors only.	

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